# 12 x 10-bit Matrix Multiplier

#### **FEATURES**

- □ 50 MHz Data and Computation Rate
- ☐ Nine Multiplier Array with 12-bit Data and 10-bit Coefficient Inputs
- ☐ Separate 16-bit Cascade Input and Output Ports
- ☐ On-board Coefficient Storage
- ☐ Four User-Selectable Filtering and Transformation Functions:
  - 3 x 3 Matrix Multiplier
  - Cascadable 9-Tap FIR Filter
  - Cascadable 3 x 3 Convolver
  - Cascadable 4 x 2 Convolver
- Replaces TRW/Raytheon/ Fairchild TMC2250
- 120-pin PQFP

#### **DESCRIPTION**

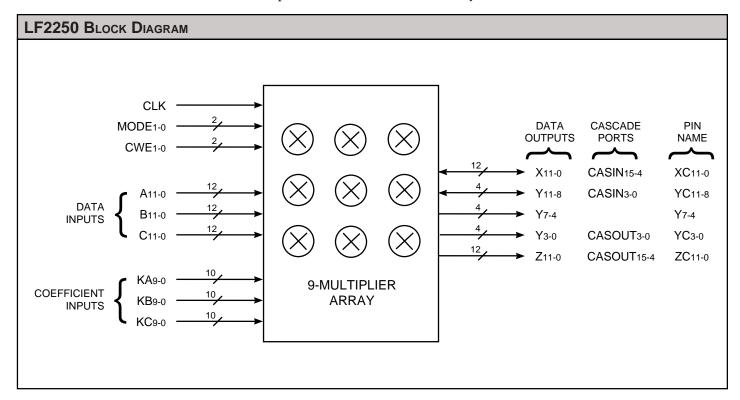
The **LF2250** is a high-speed matrix multiplier consisting of an array of nine 12 x 10-bit multipliers. Internal summing adders are also included to provide the configurations needed to implement matrix multiplications, cascadable FIR filters, and pixel convolvers.

The 3 x 3 matrix multiplier (triple dot product) configuration of the LF2250 allows users to easily perform three-dimensional perspective translations or video format conversions at real-time video rates. By using the LF2250 in this configuration, conversions can be made from the RGB (color component) format to the YIQ (quadrature encoded chrominance) or YUV (color difference) formats and vice versa (YIQ or YUV to RGB).

In addition to color space conversions, the LF2250 offers a range of selectable configurations designed for filtering applications. When configured as a 9-tap FIR filter, the LF2250 automatically selects the necessary internal bus structure and inserts the appropriate data path delay elements. In addition, a 16-bit cascade input port allows for the creation of larger filters without a reduction in throughput.

Real-time video image filtering using the convolver modes of the LF2250 can provide edge detection, texture enhancement, and detail smoothing. Both pixel convolver configurations,  $3 \times 3$  and  $4 \times 2$ , deliver high-speed data manipulation in a single chip solution. By using the 16-bit cascade input port to cascade two devices, cubic convolutions ( $4 \times 4$ -pixel) can be easily accommodated with no decrease in throughput rates.

All inputs and outputs, as well as all control lines, are registered on the rising edge of clock. The LF2250 operates at clock rates up to 50 MHz over the full commercial temperature and supply voltage ranges.



### 12 x 10-bit Matrix Multiplier

TABLE 1.	MODE SELECTION
MODE1-0	OPERATING MODE
00	3 x 3 Matrix Multiplier
01	9-Tap FIR Filter
10	3 x 3 Convolver
11	4 x 2 Convolver

#### **OPERATING MODES**

The LF2250 can realize four different user-selectable digital filtering architectures as determined by the state of the mode (MODE1-0) inputs. Upon selection of the desired function, the LF2250 automatically chooses the appropriate internal data paths and input/output bus structure. Table 1 details the modes of operation.

#### **DATA FORMATTING**

The coefficient input ports (KA, KB, KC) are 10-bit fractional two's complement format regardless of the operating mode. The data input ports (A, B, C) are 12-bit integer two's complement format regardless of the operating mode.

In the matrix multiplier mode (Mode 00), the data output ports (X, Y, Z) are 12-bit integer two's complement format. In the FIR filter and convolver modes (Modes 01, 10, 11), the X, Y, and Z ports are configured as the cascade-in (CASIN15-0) and cascade-out (CASOUT15-0) ports. These ports assume 16-bit (12-bit integer, 4-bit fractional) two's complement data on both the inputs and outputs. Table 2 shows the data port formatting for each of the four operating modes.

#### **BIT WEIGHTING**

The internal sum of products of the LF2250 can grow to 23 bits. However, in order to keep the output format of the matrix multiply mode (Mode 00) identical to the input format, the X, Y, and Z outputs are truncated to 12-bit integer words. In the filter modes (Modes 01, 10, 11), the cascade output is always half-LSB rounded to 16 bits (12 integer bits and 4 fractional bits). The user may half-LSB round the output to any size less than 16 bits by simply forcing a "1" into the bit position of the cascade input immediately below the desired LSB. For example, if half-LSB rounding to 12 bits is desired, then a "1" must be forced into the CASIN3 bit position (CASOUT4 would then be the LSB).

In all four modes, the user may adjust the bit weighting, by applying an identical scaling correction factor to both the input and output data streams. If the coefficients are rescaled, then the relative weightings of the cascade-in and cascade-out ports will differ accordingly. Figure 1 illustrates the input and output bit weightings for all four modes.

#### DATA OVERFLOW

Because the LF2250's matched input and output data formats accommodate unity gain (0 dB), input conditions that could lead to numeric overflow may exist. To ensure that no overflow conditions occur, the user must be aware of the maximum input data and coefficient word sizes allowable for each specific algorithm being performed.

#### SIGNAL DEFINITIONS

#### Power

Vcc and GND

+5 V power supply. All pins must be connected.

#### Clock

CLK — Master Clock

The rising edge of CLK strobes all enabled registers. All timing specifications are referenced to the rising edge of CLK.

#### Inputs

A11-0, B11-0, C11-0 — Data Inputs

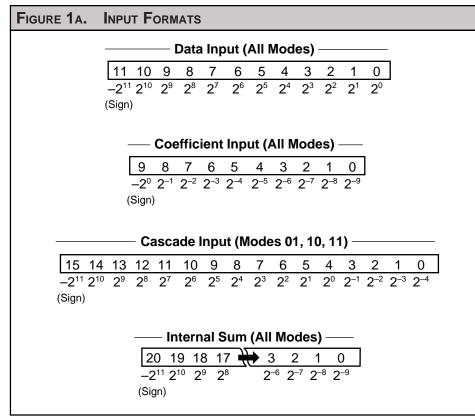
A, B, and C are the 12-bit registered data input ports. Data presented to these ports is latched into the multiplier input registers for the current operating mode (Table 1). In the filter modes (Modes 01, 10, 11), the rising edge of CLK internally right-shifts new data to the next filter tap.

KA9-0, KB9-0, KC9-0 — Coefficient Inputs

KA, KB, and KC are the 10-bit registered coefficient input ports. Data presented to these ports is latched into the corresponding internal coefficient register set defined by CWE1-0 (Table 4) on the next rising edge of CLK. Table 3 shows which coefficient registers are available for each coefficient input port.

TABLE 2.	. Dat	A PORT	FORMA <sup>-</sup>	TTING							
						PIN N	IAMES				
MODE1-0	<b>A</b> 11-0	B11-0	C11-0	KA9-0	KB9-0	KC9-0	XC11-0	YC11-8	<b>Y</b> 7-4	YC3-0	ZC11-0
00	A11-0	B11-0	C11-0	KA9-0	KB9-0	KC9-0	X11-0	Y11-8	Y7-4	Y3-0	Z11-0
01	A11-0	A11-0	NC	KA9-0	KB9-0	KC9-0	CASIN15-4	CASIN <sub>3-0</sub>	NC	CASOUT3-0	CASOUT15-4
10	A11-0	B11-0	C11-0	KA9-0	KB9-0	KC9-0	CASIN15-4	CASIN <sub>3-0</sub>	NC	CASOUT3-0	CASOUT15-4
11	A11-0	B11-0	NC	KA9-0	KB9-0	KC9-0	CASIN15-4	CASIN3-0	NC	CASOUT3-0	CASOUT15-4

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CASIN15-0 — Cascade Input

In the filter modes (Modes 01, 10, 11), the 12-bit X port and four bits of the Y port are internally reconfigured as the 16-bit registered cascade input port. Data presented to this port will be added to the internal sum of products.

#### Outputs

X11-0, Y11-0, Z11-0 — Data Outputs

X, Y, and Z are the 12-bit registered output ports for the matrix multiply mode (Mode 00). These ports are automatically reconfigured for the filter modes (Modes 01, 10, 11) as the cascade-in and cascade-out ports.

*CASOUT15-0* — *Cascade Output* 

In the filter modes (Modes 01, 10, 11), the 12-bit Z port and four bits of the Y port are internally reconfigured as the 16-bit registered cascade output port.

NOTE: The X, Y, and Z ports are automatically reconfigured by the LF2250 as the cascade-in and cascade-out ports as required for each operating mode. Because both the X and Z ports are used for the cascade ports, all X port pins and all Z port pins are labelled as XC and ZC, respectively. All Y port pins that are used for the cascade ports are labelled as YC. Those Y port pins which are not used for the cascade ports are labelled as Y.

#### **Controls**

MODE1-0 — Mode Select

The registered mode select inputs determine the operating mode of the LF2250 (Table 1) for data being input on the next clock cycle. When switching between modes, the internal pipeline latencies of the device must be observed. After switching operating modes, the user must allow enough clock cycles to pass to flush the internal registers before valid data will appear on the outputs.

*CWE1-0* — *Coefficient Write Enable* 

The registered coefficient write enable inputs determine which internal coefficient register set to update (Table 4) on the next clock cycle.

TABLE 3. C	OEFFICIENT INPUTS
INPUT PORT	REG. AVAILABLE
KA	KA1, KA2, KA3
KB	KB1, KB2, KB3
KC	KC1, KC2, KC3



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TABLE 4.	COEFF. REG. UPDATE
CWE1-0	COEFFICIENT SET
00	Hold All Registers
01	KA1, KB1, KC1
10	KA2, KB2, KC2
11	KA3, KB3, KC3

#### **DETAILS OF OPERATION**

3 x 3 Matrix Multiplier — Mode 00

In this mode, all three input ports (A, B, C) and all three output ports (X, Y, Z) are utilized to implement a 3 x 3 matrix multiplication (triple dot product). Each rounded 12-bit output is the sum of all three input words multiplied by the appropriate coefficients (Table 5). The pipeline latency for this mode is five clock cycles. Therefore, the sum of products will be output five clock cycles after the input data has been latched. New output data is subsequently available every clock cycle thereafter.

#### 9-Tap FIR Filter — Mode 01

This mode utilizes the 12-bit A and B data input ports as well as the 16-bit CASIN port. The input data should be presented to the A and B ports simultaneously. The resulting 9-sample response, which is half-LSB rounded to 16 bits, begins after five clock cycles and ends after 13 clock cycles (Table 5). The pipeline latency from the input of an impulse response to the center of the output response is nine clock cycles. The latency from the CASIN port to the CASOUT port is four clock cycles. New output data is available every clock cycle.

#### 3 x 3-Pixel Convolver — Mode 10

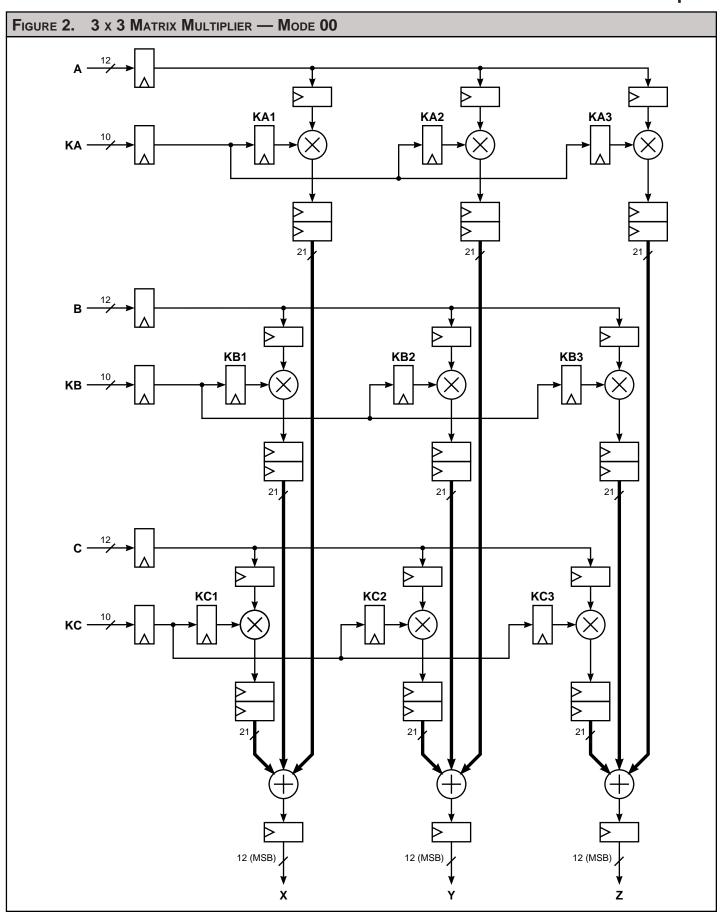
When configured in this mode, line delayed data is loaded through the A, B, and C input ports. During each cycle, a new rounded 16-bit output

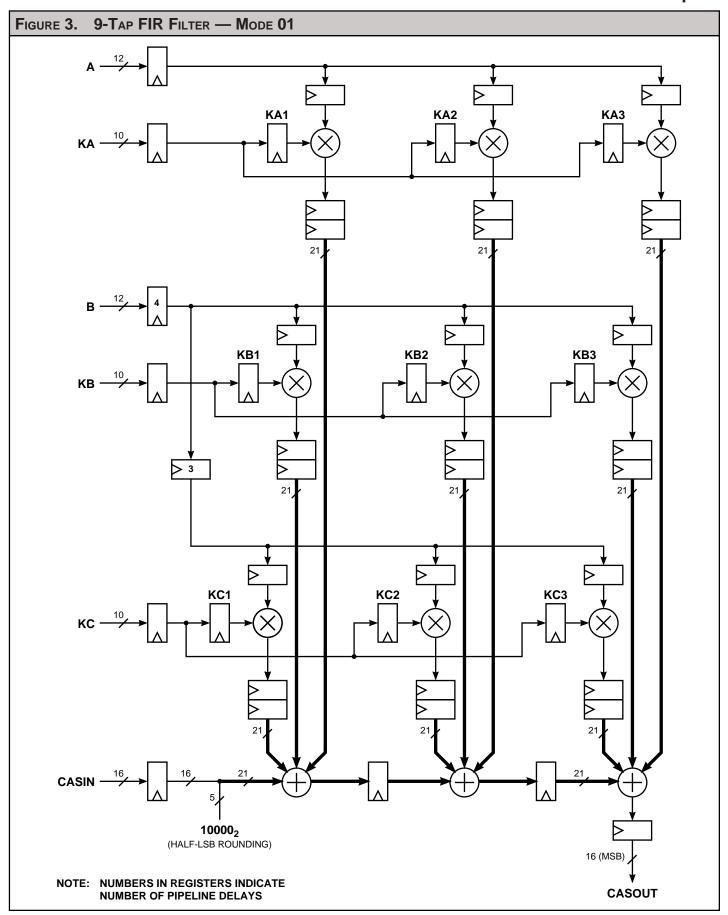
(comprising of the summation of the multiplications of the last nine data inputs with their related coefficients) becomes available (Table 5). The CASIN term is also added to each new output. The internal bus structure and pipeline delays allow new input data to be added every cycle while maintaining the structure of the filtering operation. This addition of new data every cycle produces the effect of the convolution window moving to the next pixel column.

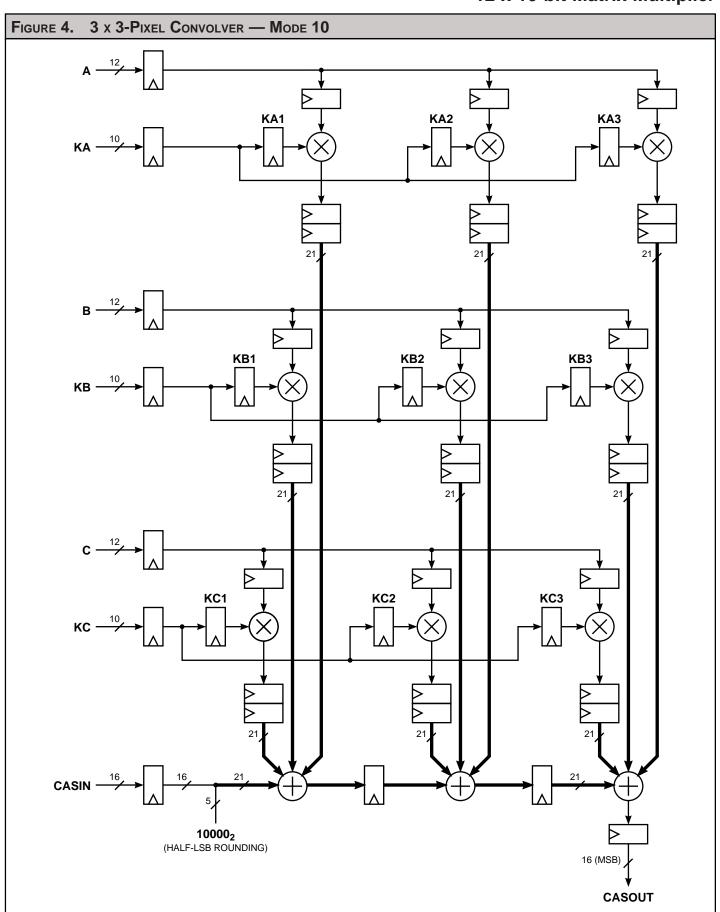
4 x 2-Pixel Convolver — Mode 11

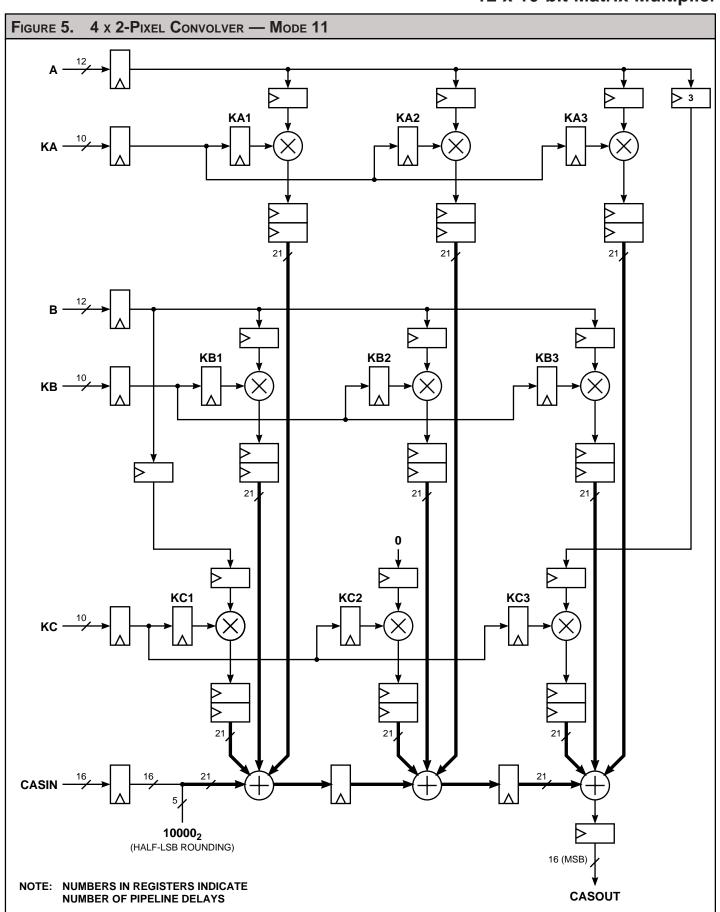
Using the A and B ports, input data is loaded and multiplied by the onboard coefficients. These products are then summed with the CASIN data and rounded to create the 16-bit output. The cascade ports allow multiple devices to be used together for use with larger kernels. As with Mode 10, each cycle results in a 16-bit output created from the products and summations performed.

Table 5. Lat	ENCY EQUATIONS
	3 x 3 Matrix Multiplier — Mode 00
X(n+	4) = A(n)KA1(n) + B(n)KB1(n) + C(n)KC1(n)
Y(n+	A(n) = A(n)KA2(n) + B(n)KB2(n) + C(n)KC2(n)
Z(n+	4) = A(n)KA3(n) + B(n)KB3(n) + C(n)KC3(n)
	9-Tap FIR Filter — Mode 01
CASOUT(n+12)	= A(n+8)KA3(n+8) + A(n+7)KA2(n+7) + A(n+6)KA1(n+6)
	+ B(n+5)KB3(n+8) + B(n+4)KB2(n+7) + B(n+3)KB1(n+6)
	+ B(n+2)KC3(n+8) + B(n+1)KC2(n+7) + B(n)KC1(n+6)
	+ CASIN(n+9)
	—— 3 x 3-Pixel Convolver — Mode 10
CASOUT(n+6)	= A(n+2)KA3(n+2) + A(n+1)KA2(n+1) + A(n)KA1(n)
	+ B(n+2)KB3(n+2) + B(n+1)KB2(n+1) + B(n)KB1(n)
	+ C(n+2)KC3(n+2) + C(n+1)KC2(n+1) + C(n)KC1(n)
	+ CASIN(n+3)
	— 4 x 2-Pixel Convolver — Mode 11
CASOUT(n+7)	= A(n+3)KA3(n+3) + A(n+2)KA2(n+2) + A(n+1)KA1(n+1)
	+ A(n)KC3(n+3) + B(n+3)KB3(n+3) + B(n+2)KB2(n+2)
	+ B(n+1)KB1(n+1) + B(n)KC1(n+1)
	+ CASIN(n+4)











MAXIMUM RATINGS Above which useful life may be impaired (Notes	s 1, 2, 3, 8)
Storage temperature	65°C to +150°C
Operating ambient temperature	–55°C to +125°C
Vcc supply voltage with respect to ground	0.5 V to +7.0 V
Input signal with respect to ground	0.5 V to Vcc + 0.5 V
Signal applied to high impedance output	0.5 V to Vcc + 0.5 V
Output current into low outputs	25 mA
Latchup current	> 400 mA

OPERATING CONDITIONS To meet spec	ified electrical and switching character	ristics
Mode	Temperature Range (Ambient)	Supply Voltage
Active Operation, Commercial	0°C to +70°C	4.75 V ≤ <b>V</b> CC ≤ 5.25 V
Active Operation, Military	−55°C to +125°C	$4.50 \text{ V} \le \text{V} \text{CC} \le 5.50 \text{ V}$

ELECTRI	CAL CHARACTERISTICS Ove	er Operating Conditions (Note 4)				
Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
<b>V</b> OH	Output High Voltage	<b>V</b> cc = Min., <b>I</b> OH = -2.0 mA	2.4			V
<b>V</b> OL	Output Low Voltage	Vcc = Min., IoL = 4.0 mA			0.4	V
<b>V</b> IH	Input High Voltage		2.0		<b>V</b> CC	V
<b>V</b> IL	Input Low Voltage	(Note 3)	0.0		0.8	V
lıx	Input Current	Ground ≤ VIN ≤ VCC (Note 12)			±10	μA
loz	Output Leakage Current	(Note 12)			±40	μA
ICC1	Vcc Current, Dynamic	(Notes 5, 6)			160	mA
ICC2	Vcc Current, Quiescent	(Note 7)			12	mA
CIN	Input Capacitance	<b>T</b> A = 25°C, f = 1 MHz			10	pF
COUT	Output Capacitance	<b>T</b> A = 25°C, f = 1 MHz			10	pF

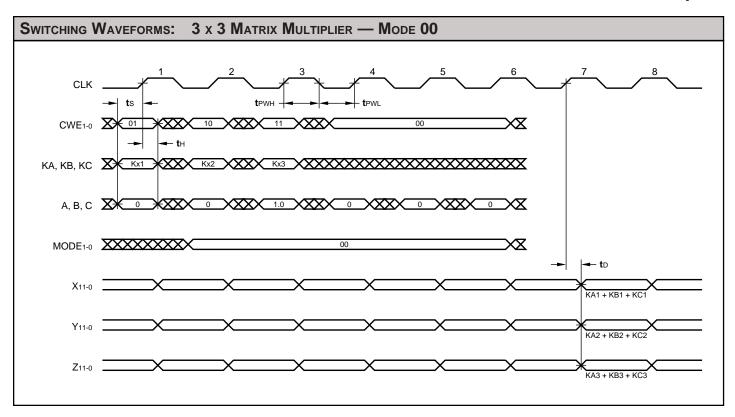


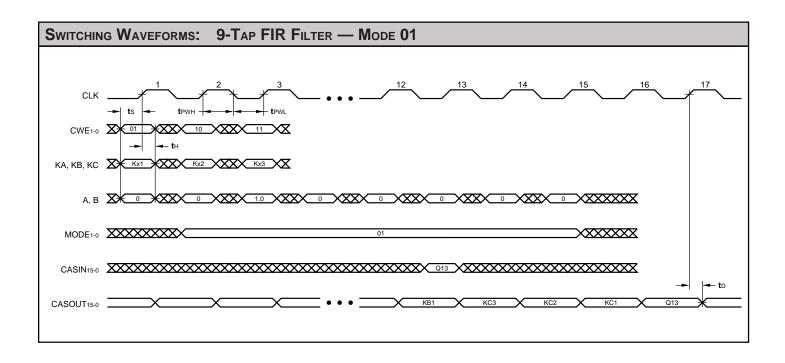
## 12 x 10-bit Matrix Multiplier

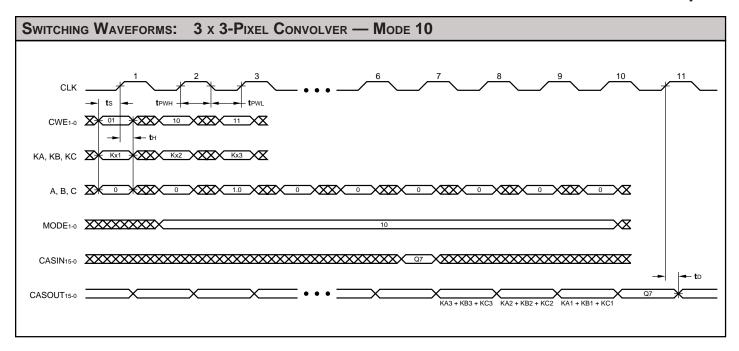
### **SWITCHING CHARACTERISTICS**

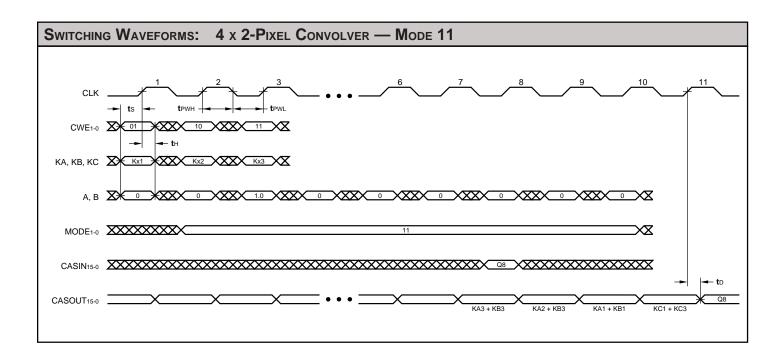
Сомме	RCIAL OPERATING RANGE (0°C to +	<b>70°C)</b> Notes 9, 10 (ns	 s)				
				LF2	250–		
		/////33	*///////	2	25	2	20
Symbol	Parameter	//Min//	Max	Min	Max	Min	Max
tCYC	Cycle Time	//33///		25		20	
<b>t</b> PWL	Clock Pulse Width Low	15		10		6	
<b>t</b> PWH	Clock Pulse Width High	10//		10		8	
ts	Input Setup Time	8///		6		6	
t⊢	Input Hold Time	0//0		0		0	
<b>t</b> D	Output Delay		18		16		15

MILITAR	Y OPERATING RANGE (-55°C to +125°C) Note	es 9, 10 (ns)			
			LF2	250–	
		3	3*//////	25	<b>5</b> *//////
Symbol	Parameter	Min	Max	Min	Max
<b>t</b> CYC	Cycle Time	//33///		25	
<b>t</b> PWL	Clock Pulse Width Low	//15///		10	
<b>t</b> PWH	Clock Pulse Width High	//10//		10	
ts	Input Setup Time	//12///		9	
<b>t</b> H	Input Hold Time	///2///		2	
<b>t</b> D	Output Delay		25		20//









### 12 x 10-bit Matrix Multiplier

#### **NOTES**

- 1. Maximum Ratings indicate stress specifications only. Functional operation of these products at values beyond those indicated in the Operating Conditions table is not implied. Exposure to maximum rating conditions for extended periods may affect reliability.
- 2. The products described by this specification include internal circuitry designed to protect the chip from damaging substrate injection currents and accumulations of static charge. Nevertheless, conventional precautions should be observed during storage, handling, and use of these circuits in order to avoid exposure to excessive electrical stress values.
- 3. This device provides hard clamping of transient undershoot and overshoot. Input levels below ground or above VCC will be clamped beginning at -0.6 V and VCC + 0.6 V. The device can withstand indefinite operation with inputs in the range of -0.5 V to +7.0 V. Device operation will not be adversely affected, however, input current levels will be well in excess of 100 mA.
- 4. Actual test conditions may vary from those designated but operation is guaranteed as specified.
- 5. Supply current for a given application can be accurately approximated by:

 $\frac{NCV^2F}{4}$ 

where

N = total number of device outputs

C = capacitive load per output

V = supply voltage

F = clock frequency

- 6. Tested with all outputs changing every cycle and no load, at a 20 MHz clock rate.
- 7. Tested with all inputs within 0.1 V of **V**CC or Ground, no load.
- 8. These parameters are guaranteed but not 100% tested.

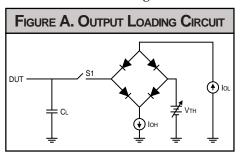
9. AC specifications are tested with input transition times less than 3 ns, output reference levels of 1.5 V (except tDIS test), and input levels of nominally 0 to 3.0 V. Output loading may be a resistive divider which provides for specified IOH and IOL at an output voltage of VOH min and VOL max respectively. Alternatively, a diode bridge with upper and lower current sources of IOH and IOL respectively, and a balancing voltage of 1.5 V may be used. Parasitic capacitance is 30 pF minimum, and may be distributed.

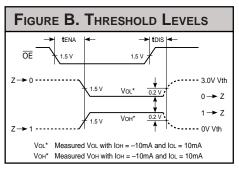
This device has high-speed outputs capable of large instantaneous current pulses and fast turn-on/turn-off times. As a result, care must be exercised in the testing of this device. The following measures are recommended:

- a. A  $0.1~\mu F$  ceramic capacitor should be installed between VCC and Ground leads as close to the Device Under Test (DUT) as possible. Similar capacitors should be installed between device VCC and the tester common, and device ground and tester common.
- b. Ground and VCC supply planes must be brought directly to the DUT socket or contactor fingers.
- c. Input voltages should be adjusted to compensate for inductive ground and  $\mathbf{V}$ CC noise to maintain required DUT input levels relative to the DUT ground pin.
- 10. Each parameter is shown as a minimum or maximum value. Input requirements are specified from the point of view of the external system driving the chip. Setup time, for example, is specified as a minimum since the external system must supply at least that much time to meet the worst-case requirements of all parts. Responses from the internal circuitry are specified from the point of view of the device. Output delay, for example, is specified as a maximum since worst-case operation of any device always provides data within that time.

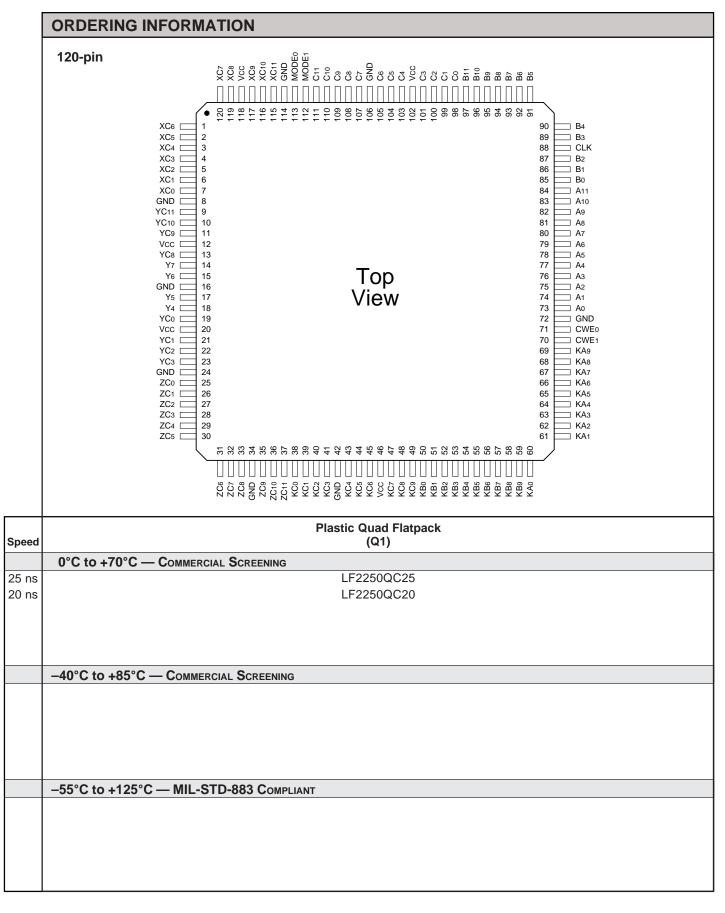
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- 11. For the tena test, the transition is measured to the 1.5 V crossing point with datasheet loads. For the tDIS test, the transition is measured to the  $\pm 200 \,\mathrm{mV}$  level from the measured steady-state output voltage with  $\pm 10 \,\mathrm{mA}$  loads. The balancing voltage, VTH, is set at 3.5 V for Z-to-0 and 0-to-Z tests, and set at 0 V for Z-to-1 and 1-to-Z tests.
- 12. These parameters are only tested at the high temperature extreme, which is the worst case for leakage current.









B	B	120-pin		1//1//	2	3	4	5	6	7	8	9	10	11	12	13
B	B		A											/ <u>/</u> ///		12
C	C		В	XC7	XC9	XC10	MODE:	C11	C8/ (2)/	C7 CY	C5	C3	(C1 (2)	B10	B7	(B4)
D	D		c	XC4	XC5	XC8	XC11	MODE1	C9	C6	C4	C2	B11 (2)	B9	B6	B2
F	F		D	XC1	XC2	XC6	Vcc	GND	C10	GND	Vcc	C <sub>0</sub>	B8	B5	B3	B1
J   C   C   C   C   C   C   C   C   C	Victorial   Vict		, l	YC11	XC <sub>0</sub>	XC3			KEY					CLK	Bo	/A10/
J   C   C   C   C   C   C   C   C   C	Victorial   Vict			YC9	YC10	GND								A11	A9	A8
J   C   C   C   C   C   C   C   C   C	Victorial   Vict			Ý1 Č)	YC8	Vcc			/////	/////	/////	e		A7	A6	A5
J   C   C   C   C   C   C   C   C   C	Victorial   Vict			Y5	Y6	GND							t)	A3	A2	A4
YC3   ZC0   ZC3   KA4   KA7   KA8	YC3   ZC0   ZC3   KA4   KA7   KA9			Y4	YC <sub>0</sub>	Vcc									Ao (2)	A1
M   C2   C7   ZC9   ZC11   KC2   KC4   KC6   KC8   KB2   KB5   KA2   KA3   N   C   C   C   C   C   C   C   C   C				YC1	YC2	GND									CWE1	
M   C2   C7   ZC9   ZC11   KC2   KC4   KC6   KC8   KB2   KB5   KA2   KA3   N   C   C   C   C   C   C   C   C   C				YC3	ZCo	ZC3								KA4	KA7	KA9
Discontinued Package  Ceramic Pin Grid Array (G4)  0°C to +70°C — Commercial Screening	Discontinued Package  Ceramic Pin Grid Array (G4)  C to +70°C — Commercial Screening			ZC1	ZC4	ZC6	GND	KC <sub>0</sub>	GND	Vec	KB <sub>0</sub>	KB4	KB8		KA5	KA6
Discontinued Package  Ceramic Pin Grid Array (G4)  0°C to +70°C — Commercial Screening	Discontinued Package  Ceramic Pin Grid Array (G4)  C to +70°C — Commercial Screening  C to +125°C — Commercial Screening			ZC2	ZC7	ZC9	ZC11	KC <sub>2</sub>	KC4	KC6	KC9	KB2	KB <sub>5</sub>	KB9	KA2	/KA3/
Ceramic Pin Grid Array (G4)  0°C to +70°C — COMMERCIAL SCREENING  55°C to +125°C — COMMERCIAL SCREENING	C to +70°C — COMMERCIAL SCREENING  C to +125°C — COMMERCIAL SCREENING			ŹĆ5	ZC8	ZC10	KC1	KC3	KC <sub>5</sub>	KC <sub>7</sub>	KC8	KB <sub>1</sub>	КВз	KB6	KB7	KAo
0°C to +70°C — Commercial Screening  -55°C to +125°C — Commercial Screening	C to +70°C — COMMERCIAL SCREENING  °C to +125°C — COMMERCIAL SCREENING						E	Discor	ntinu	ed Pa	ckag	e				
0°C to +70°C — COMMERCIAL SCREENING  55°C to +125°C — COMMERCIAL SCREENING	C to +70°C — COMMERCIAL SCREENING  °C to +125°C — COMMERCIAL SCREENING		<u> </u>		////	////	C	eram			l Arra	ay	////	////	////	<u>////</u>
									٠,	7,						
		0°C to +70°C -	— Сомме	RCIAL S	CREE	NING										
55°C to +125°C — MIL-STD-883 Compliant	°C to +125°C — MIL-STD-883 COMPLIANT						١G									
55°C to +125°C — MIL-STD-883 COMPLIANT	°C to +125°C — MIL-STD-883 COMPLIANT						NG									
55°C to +125°C — MIL-STD-883 COMPLIANT	°C to +125°C — MIL-STD-883 COMPLIANT						NG									
JJ C to T123 C — WILL-3 I D-003 COMPLIANT	C to T125 C — WILL-STD-005 CUMPLIANT						NG									
		–55°C to +125°(	С — Сом	IMERCI <i>A</i>	il <b>S</b> ce	REENIN										
		–55°C to +125°(	С — Сом	IMERCI <i>A</i>	il <b>S</b> ce	REENIN										